



## Design For Manufacturability - Capability Matrix

### Design Pitch

<b>D U T  A R E A</b>		1mm	.8mm	.65mm	.5mm	.4mm
		(.0394")	(.0315")	(.0256")	(.0197")	(.0157")
	Max Drill Size	.020"	.012"	.008"	.006"	.004"
	Trace Width	.0065"	.006"	.0045"	.004"	.0035"
	Hole to Copper	.0065"	.0065"	.0065"	.0048"	.0041"
	Pad/Annular Ring	.030"/.005"	.020"/.004"	.014"/.003"	.010"/.002"	.007"/.0015"

**Notes:**

1/2 ounce copper on the internal layers is preferred,  
if not on the planes, at least on the signal layers.

If one ounce copper is used on signal layers,  
some of the line widths may need to be adjusted.

**DFM Rules:**

Minimum Lines:	3.0 mil (5 mil is preferred)
Minimum Space:	3.0 mil (5 mil is preferred)
Minimum Drilled Hole:	4.0 mil
Minimum Drilled Hole to Copper:	4.1 mil
Minimum Dielectric Space:	2.0 mil
Maximum Aspect Ratio:	32:1
Finished Board Thickness:	+/- 5%
Impedance:	+/- 5%